

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

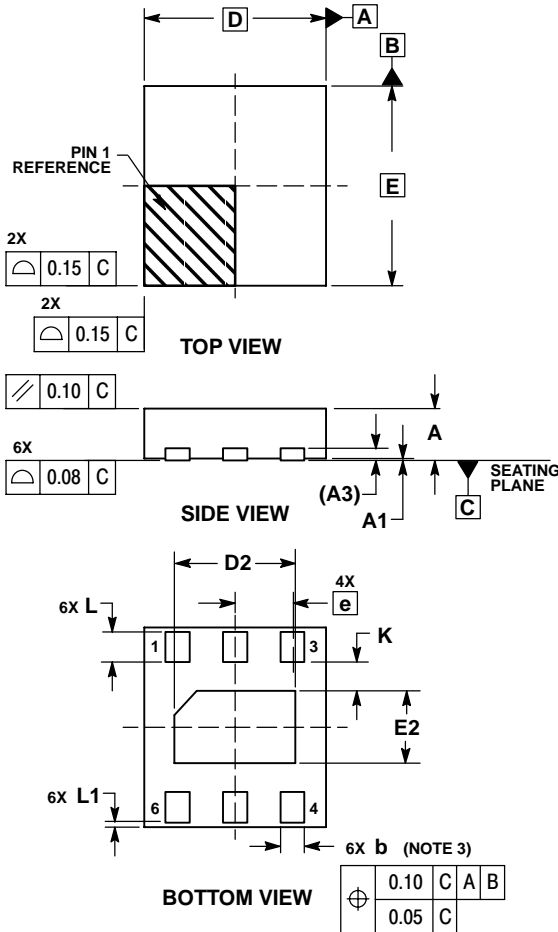
ON Semiconductor®



SCALE 2:1

DFN6 3x3.3 MM, 0.95 PITCH
CASE 506AX-01
ISSUE O

DATE 20 JAN 2006

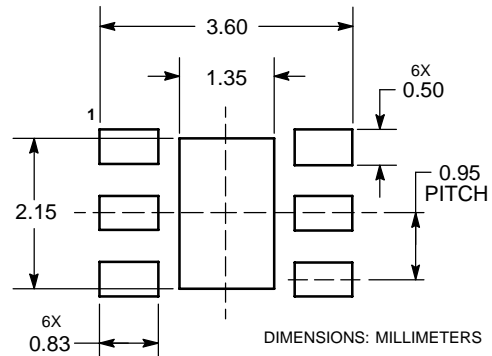


NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.80	---	0.90
A1	0.00	---	0.05
A3	0.20 REF		
b	0.30	---	0.40
D	3.00 BSC		
D2	1.90	---	2.10
E	3.30 BSC		
E2	1.10	---	1.30
e	0.95 BSC		
K	0.20	---	---
L	0.40	---	0.60
L1	0.00	---	0.15

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	DFN6 3X3.3 MM, 0.95 PITCH	PAGE 1 OF 2

